

Jinqing Xiao

List of Publications by Year in descending order

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citing authors

#	ARTICLE	IF	CITATIONS
1	Research on Flip-Chip Bonding Process and Thermal Cycle Reliability Simulation of 3-D Stacked Structure. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2022, 12, 51-58.	2.5	6
2	Effects of Kovar-4J29 Cylinder Resonance on Ultrasonic Wire Bonding. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 153-160.	2.5	4
3	Design and Fabrication of Leadless Package Structure for Pressure Sensors. Journal of Electronic Packaging, Transactions of the ASME, 2022, 144, .	1.8	3
4	Characterization of a Probe Test System With Micro-Magnetorheological Flexible Loading. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1666-1673.	2.5	2
5	High-G Shock Reliability of 3-D Integrated Structure Microsystem Based on Finite Element Simulation. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 1243-1249.	2.5	1
6	Effect of bump shapes on the electromigration reliability of copper pillar solder joints. , 2021, , .		1
7	Electromechanical Performance of Microprobe Test With Cuboid Magnetorheological Damper in Microelectronic Packaging. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2022, 12, 723-730.	2.5	0